L Number	Hits	Search Text	DB	Time stamp
1	87	stack near4 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 09:31
2	6	(stack near4 heat adj sink.ti,ab,clm.) and (rubber or elastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 10:14
3	5	(stack near4 heat adj sink.ti,ab,clm.) and (rubber or elastic or spacer) near12 (insulat$3 or isolat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 10:15
8	29	riser near6 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 11:04
9	2	riser near10 heat adj sink near10 (liquid or flow or fluid or coolant or water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 11:05
10	28	riser near10 (liquid or flow or fluid or coolant or water) and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 11:53
13	2	("5794839").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 13:19
14	7	semiconductor adj laser.ti,ab,clm. and heat adj sink.ti,ab,clm. and (stack or stacked) near3 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:10
15	1	heat adj sink.ti,ab,clm. and (stack or stacked) near3 heat adj sink and (upper adj electrode near20 lower adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:08
16	2	semiconductor.ti,ab,clm. and heat adj sink.ti,ab,clm. and (stack or stacked) adj heat adj "sinks" and (top upper) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:22
20	36		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:28
21	9		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 15:21
23	174	257/625	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:09

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24	8124	((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:23
26	1	(((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (riser guide guiding) near12 (flow liquid water coolant) and (stack stacked) near2 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:13
27	2	(((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and stacked adj heat adj sinks	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:39
28	10	(((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:45
32	0	((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks) and (first upper top) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:46
33	2	((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:49
34	0	stacked adj heat adj sinks.ti,ab,clm. and semiconductor adj2 (element device) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:51
35	4	(stack stacking stacked) near12 heat adj sinks and semiconductor adj2 (element device) and ((top upper) adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:31
36	2	("4631573").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 17:31
37	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 17:31
38	1	stacked.ti,ab,clm. and heat adj sink.ti,ab,clm. and (electronic or semiconductor) adj (device or element) and "in series"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:34
39	0	semiconductor adj laser.ti,ab,clm. and (372/4$1.ccls. or 372/50.ccls.) and stacked and "in series"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:35
40	74	semiconductor adj laser.ti,ab,clm. and (372/4$1.ccls. or 372/50.ccls.) and stacked and series	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:53

41	8	stacked near3 active near3 region near3 monolithic near3 laser near3 array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:55
42	2	("5157680").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:55
43	20	stacked near12 active near12 laser near12 array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 20:35
44	2	("4791634").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:07
45	2	("6144683").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:08
46	0	("jp-8181392$-$.did.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:09
47	2	jp-08181392$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:09
48	0	bell.in. and morrison.in. and law.in. and malcolm.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:11
49	1	gb-1597829$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:12
–	2	jp-09102568$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 09:31
–	2	jp-08227953$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 16:22
–	2	jp-08139479$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 16:24
–	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 16:24
–	2008	((372/34) or (372/35) or (372/36)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:24

–	996	heat adj sink.ti. and 257/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 07:45
–	33	heat adj sink.ti. and liquid.ti,ab. and 257/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:28
–	20	(((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and laser.ti,ab. and heat adj sink.ti,ab. and (liquid or water).ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 08:27
–	8	(US-6307871-$ or US-5801442-$ or US-4791634-$ or US-4712609-$ or US-3764935-$).did. or (US-20010004370-$).did. or (JP-02257683-$ or JP-63073584-$).did.	USPAT; US-PGPUB; JPO	2002/08/07 08:49
–	388	(257/365).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/08 15:44
–	6068	(((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:50
–	307	(((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:52
–	110	((((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:53
–	63	((((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:55
–	40	(((((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))) and semiconductor	USPAT	2002/08/09 12:56
–	44	(((((((372/34) or (372/35) or (372/36)).CCLS.) or (((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 13:32
–	1	heat adj sink.ti. and liquid.ti,ab. and 372/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:29

–	33	heat adj sink.ti. and 372/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:29
–	10026	heat adj sink and upper near12 lower	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:24
–	710	heat adj sink.ti. and upper near12 lower	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:25
–	70	heat adj sink.ti. and upper near12 lower near12 (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:26
–	30	heat adj sink.ti. and upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:31
–	2	heat adj sink.ti. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:33
–	2	heat adj sink.ti,ab. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:34
–	2	heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:35
–	4	heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower near6 (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:52
–	6	heat adj sink.ti,ab. and (groove or trench) near18 ((upper near18 lower) near18 (face or main adj surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:54
–	4163	((257/712) or (257/713) or (257/714) or (257/715)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 14:08
–	1156	(372/34).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:25
–	423	(372/35).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:25
–	661	(372/36).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26

-	1884	(257/712).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	958	(257/713).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	1193	(257/714).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	493	(257/715).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	6144	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:27
-	4269	(((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)) and (heat adj removal or heat adj sink or coolant or cooling)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:28
-	3590	(((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)) and (heat adj removal or heat adj sink or coolant or cooling).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:29
-	1280	(((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)) and (heat adj removal or heat adj sink or coolant or cooling).ti,ab,clm. and liquid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:29
-	263	(((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)) and (heat adj removal or heat adj sink or coolant or cooling).ti,ab,clm. and liquid and (groove or trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:30
-	27	(US-6198758-$ or US-6310900-$ or US-3654528-$ or US-4807022-$ or US-5729052-$ or US-5783862-$ or US-5864176-$ or US-5918665-$ or US-6157077-$ or US-6274912-$ or US-6347050-$ or US-5801442-$ or US-4712609-$ or US-3764935-$ or US-5241450-$ or US-4791634-$ or US-5812570-$ or US-6307871-$).did. or (US-20010004370-$).did. or (JP-02257683-$ or JP-63073584-$ or JP-09102568-$ or JP-08227953-$ or JP-08139479-$).did. or (JP-09102568-$ or EP-715352-$ or JP-08139479-$).did.	USPAT; US-PGPUB; JPO; DERWENT	2002/08/23 18:39

—	5	((US-6198758-$ or US-6310900-$ or US-3654528-$ or US-4807022-$ or US-5729052-$ or US-5783862-$ or US-5864176-$ or US-5918665-$ or US-6157077-$ or US-6274912-$ or US-6347050-$ or US-5801442-$ or US-4712609-$ or US-3764935-$ or US-5241450-$ or US-4791634-$ or US-5812570-$ or US-6307871-$).did. or (US-20010004370-$).did. or (JP-02257683-$ or JP-63073584-$ or JP-09102568-$ or JP-08227953-$ or JP-08139479-$).did. or (JP-09102568-$ or EP-715352-$ or JP-08139479-$).did.) and laser adj diode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 18:39
—	2	("4791634").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 14:12
—	0	jp-8227953$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 14:13
—	2	jp-08227953$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 14:13 .
—	21	zengerle.in. and heat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 15:25
—	4	zengerle.in. and power adj semiconductor adj component	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 15:26
—	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 14:06
—	127	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:18
—	103	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:24
—	103	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and heat adj sink.ti,ab,clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:24

–	4	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and (groove or slit) near12 heat adj sink	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:32
–	5	(((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and (groove or slit) near12 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:48
–	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:49
–	1627	(257/678).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:15
–	36	((257/678).CCLS.) and heat adj sink.ti,ab,clm. and (liquid or water or flow or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:39
–	109	hayashi.in. and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:40
–	18	hayashi.in. and laser.ti,ab,clm. and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:42
–	2	jp-09102568$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:54
–	1442	heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:56
–	3	lsi and (heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:59
–	2	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:00
–	4	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:09

-	491	semiconductor adj laser near6 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:09
-	249	semiconductor adj laser near3 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:11
-	1	(semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and liquid adj coolant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:12
-	35	(semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:03
-	2	jp-08227953$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 14:14
-	2	("3351698").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:22
-	0	("heat adj sink near20 laser near20 electrode near20 copper").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:22
-	19	heat adj sink near20 laser near20 electrode near20 copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:53
-	0	top adj electrode near12 bottom adj electrode near20 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:55
-	44	"electrodes" near12 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:56
-	29	"electrodes" near6 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:56
-	8	"electrodes" near3 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:02
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:02
-	2118	heat adj sink near12 electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:07

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–	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:18
–	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:34
–	2	guiding adj (hole or through-hole or aperture) near12 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:51
–	115	(hole or through-hole or aperture) near12 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:53
–	103	(hole or through-hole or aperture) near6 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:55
–	57	(hole or through-hole or aperture) near3 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:56
–	3	(hole or through-hole or aperture) near3 (guide or guiding) near12 heat adj sink near12 (liquid or water or coolant) and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:59
–	2	jp-09102568$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:00
–	2	jp-08227953$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:01
–	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:30
–	0	("heat adj sink near12 (leak or leakage or leaking) near12 rubber").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:30
–	0	heat adj sink near12 (leak or leakage or leaking) near12 rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:31
–	0	heat adj sink near12 (leak or leakage or leaking) near12 (elastic rubber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:32
–	20	heat adj sink near12 (leak or leakage or leaking) near12 (elastic rubber insulating insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 21:09

-	2 jp-08181392$-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 21:09

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